

MICRON**MT5C1008**
128K x 8 SRAM

T-46-23-14

SRAM**128K x 8 SRAM**

WITH OUTPUT ENABLE

5 VOLT SRAM**FEATURES**

- High speed: 12*, 15*, 17, 20, 25, 35 and 45ns
- High-performance, low-power, CMOS double-metal process
- Single +5V $\pm 10\%$ power supply
- Easy memory expansion with $\overline{CE1}$, $CE2$ and \overline{OE} options
- All inputs and outputs are TTL compatible
- Fast \overline{OE} access time: 8ns

OPTIONS

- Timing
 - 12ns access
 - 15ns access
 - 17ns access
 - 20ns access
 - 25ns access
 - 35ns access
 - 45ns access

MARKING

-12*
-15*
-17
-20
-25
-35
-45

- Packages

Plastic DIP (400 mil)
Plastic SOJ (400 mil)

None
DJ

NOTE: Available in ceramic packages tested to meet military specifications. Please refer to Micron's *Military Data Book*.

- 2V data retention L
- 2V data retention, low power LP
- Temperature
 - Industrial (-40°C to +85°C) IT
 - Automotive (-40°C to +125°C) AT
 - Extended (-55°C to +125°C) XT

- Part Number Example: MT5C1008DJ-25 LP IT

*Preliminary

GENERAL DESCRIPTION

The Micron SRAM family employs high-speed, low-power CMOS designs using a four-transistor memory cell. Micron SRAMs are fabricated using double-layer metal, double-layer polysilicon technology.

For flexibility in high-speed memory applications, Micron offers dual chip enables ($\overline{CE1}$, $CE2$) and an output enable (\overline{OE}). This enhancement can place the outputs in High-Z for additional flexibility in system design.

Writing to these devices is accomplished when write enable (\overline{WE}) and $\overline{CE1}$ inputs are both LOW and $CE2$ is

PIN ASSIGNMENT (Top View)**32-Pin DIP**
(SA-7, SA-8)

NC	1	32	Vcc
A16	2	31	A15
A14	3	30	CE2
A12	4	29	WE
A7	5	28	A13
A8	6	27	A8
A5	7	26	A9
A4	8	25	A11
A3	9	24	\overline{OE}
A2	10	23	A10
A1	11	22	$\overline{CE1}$
A0	12	21	DQ8
DQ1	13	20	DQ7
DQ2	14	19	DQ6
DQ3	15	18	DQ5
Vss	16	17	DQ4

32-Pin SOJ
(SD-5)

NC	1	32	Vcc
A16	2	31	A15
A14	3	30	CE2
A12	4	29	WE
A7	5	28	A13
A6	6	27	A8
A5	7	26	A9
A4	8	25	A11
A3	9	24	\overline{OE}
A2	10	23	A10
A1	11	22	$\overline{CE1}$
A0	12	21	DQ8
DQ1	13	20	DQ7
DQ2	14	19	DQ6
DQ3	15	18	DQ5
Vss	16	17	DQ4

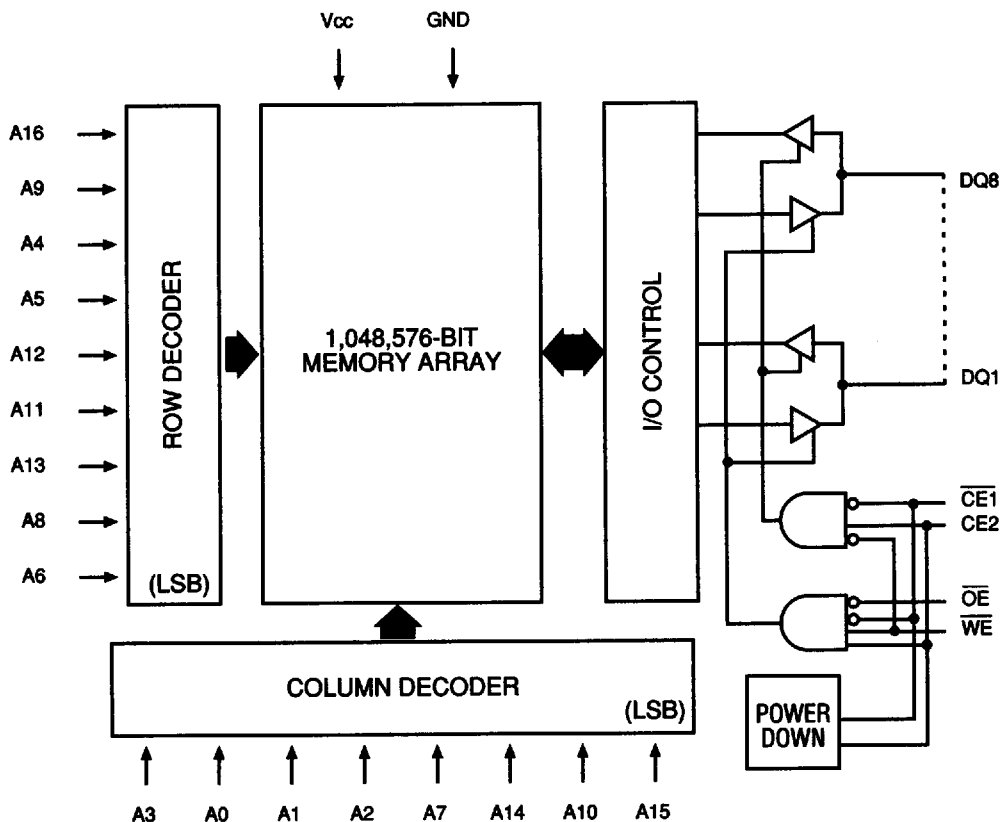
HIGH. Reading is accomplished when \overline{WE} and $CE2$ remain HIGH and $\overline{CE1}$ and \overline{OE} go LOW. The device offers reduced power standby modes when disabled. This allows system designers to meet low standby power requirements.

The "L" and "LP" versions each provide a 70% reduction in CMOS standby current (I_{SB2}) over the standard version. The "LP" version also provides a 90% reduction in TTL standby current (I_{SB1}). This is achieved by including gated inputs on the \overline{WE} , \overline{OE} and address lines. The gated inputs also facilitate the design of battery backed systems where the designer needs to protect against inadvertent battery current drain during power-down, when inputs may be at undefined levels.

All devices operate from a single +5V power supply and all inputs and outputs are fully TTL compatible.

MICRON**MT5C1008**
128K x 8 SRAM**FUNCTIONAL BLOCK DIAGRAM**

T-46-23-14

5 VOLT SRAM

NOTE: The two least significant row address bits (A8 and A6) are encoded using a gray code.

TRUTH TABLE

MODE	OE	CE1	CE2	WE	DQ	POWER
STANDBY	X	H	X	X	HIGH-Z	STANDBY
STANDBY	X	X	L	X	HIGH-Z	STANDBY
READ	L	L	H	H	Q	ACTIVE
READ	H	L	H	H	HIGH-Z	ACTIVE
WRITE	X	L	H	L	D	ACTIVE

MICRON**MT5C1008**
128K x 8 SRAM**T-46-23-14****ABSOLUTE MAXIMUM RATINGS***

Voltage on Vcc Supply Relative to Vss -1V to +7V
 Storage Temperature (Plastic) -55°C to +150°C
 Power Dissipation 1W
 Short Circuit Output Current 50mA
 Voltage on any pin relative to Vss -1V to Vcc +1V

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

ELECTRICAL CHARACTERISTICS AND RECOMMENDED DC OPERATING CONDITIONS(0°C ≤ T_A ≤ 70°C; Vcc = 5V ±10%)

DESCRIPTION	CONDITIONS	SYMBOL	MIN	MAX	UNITS	NOTES
Input High (Logic 1) Voltage		V _{IH}	2.2	Vcc +1	V	1
Input Low (Logic 0) Voltage		V _{IL}	-0.5	0.8	V	1, 2
Input Leakage Current	0V ≤ V _{IN} ≤ Vcc	I _{LI}	-5	5	μA	
Output Leakage Current	Output(s) Disabled 0V ≤ V _{OUT} ≤ Vcc	I _{LO}	-5	5	μA	
Output High Voltage	I _{OH} = -4.0mA	V _{OH}	2.4		V	1
Output Low Voltage	I _{OL} = 8.0mA	V _{OL}		0.4	V	1
Supply Voltage		Vcc	4.5	5.5	V	1

				MAX								
DESCRIPTION	CONDITIONS	SYMBOL	TYP	-12+	-15+	-17	-20	-25	-35	-45	UNITS	NOTES
Power Supply Current: Operating	CE2 ≥ V _{IH} ; CE1 ≤ V _{IL} ; V _{CC} = MAX f = MAX = 1/10RC Outputs Open	I _{CC}	95	190	165	155	140	125	115	110	mA	3, 15
Power Supply Current: Standby	CE2 ≤ V _{IH} or CE1 ≥ V _{IH} ; V _{CC} = MAX f = MAX = 1/10RC Outputs Open	I _{SB1}	17	45	40	40	35	30	25	25	mA	15
	"LP" Version Only	I _{SB1}	1.3	3	3	3	3	3	3	3	mA	15
	CE2 ≤ V _{SS} + 0.2V; CE1 ≥ V _{CC} - 0.2V; V _{CC} = MAX V _{IN} ≤ V _{SS} + 0.2V or V _{IN} ≥ V _{CC} - 0.2V; f = 0	I _{SB2}	0.4	5	5	5	5	5	5	5	mA	15
	"L" and "LP" Versions Only	I _{SB2}	0.3	1.5	1.5	1.5	1.5	1.5	1.5	1.5	mA	15

*Preliminary

CAPACITANCE

DESCRIPTION	CONDITIONS	SYMBOL	MAX	UNITS	NOTES
Input Capacitance	T _A = 25°C; f = 1 MHz Vcc = 5V	C _I	8	pF	4
Output Capacitance		C _O	8	pF	4

MICRON**MT5C1008**
128K x 8 SRAM**T-46-23-14****ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS**(Note 5, 14) ($0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$; $V_{CC} = 5V \pm 10\%$)**5 VOLT SRAM**

DESCRIPTION		-12*		-15*		-17		-20		-25		-35		-45			
	SYM	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNITS	NOTES
READ Cycle																	
READ cycle time	t _{RC}	12		15		17		20		25		35		45		ns	
Address access time	t _{AA}		12		15		17		20		25		35		45	ns	
Chip Enable access time	t _{ACE}		12		15		17		20		25		35		45	ns	
Output hold from address change	t _{OH}	3		3		3		3		5		5		5		ns	
Chip Enable to output in Low-Z	t _{LZCE}	3		5		5		5		5		5		5		ns	7
Chip disable to output in High-Z	t _{HZCE}		5		6		7		8		10		15		18	ns	6, 7
Chip Enable to power-up time	t _{PU}	0		0		0		0		0		0		0		ns	
Chip disable to power-down time	t _{PD}		12		15		17		20		25		35		45	ns	
Output Enable access time	t _{AOE}		4		5		5		6		8		12		15	ns	
Output Enable to output in Low-Z	t _{LZOE}	0		0		0		0		0		0		0		ns	
Output disable to output in High-Z	t _{HZOE}		4		5		5		6		10		12		15	ns	6
WRITE Cycle																	
WRITE cycle time	t _{WC}	12		15		17		20		25		35		45		ns	
Chip Enable to end of write	t _{CW}	8		10		12		12		15		20		25		ns	
Address valid to end of write	t _{AW}	8		10		12		12		15		20		25		ns	
Address setup time	t _{AS}	0		0		0		0		0		0		0		ns	
Address hold from end of write	t _{AH}	0		0		0		0		0		0		0		ns	
WRITE pulse width	t _{WP1}	8		9		12		12		15		20		25		ns	
WRITE pulse width	t _{WP2}	10		12		13		15		15		20		25		ns	
Data setup time	t _{DS}	6		7		8		8		10		15		20		ns	
Data hold time	t _{DH}	0		0		0		0		0		0		0		ns	
Write disable to output in Low-Z	t _{LZWE}	3		3		3		3		3		3		3		ns	7
Write Enable to output in High-Z	t _{HZWE}		5		6		7		8		10		15		18	ns	6, 7

*Preliminary


MT5C1008
128K x 8 SRAM
T-46-23-14
AC TEST CONDITIONS

Input pulse levels	Vss to 3.0V
Input rise and fall times	5ns
Input timing reference levels	1.5V
Output reference levels	1.5V
Output load	See Figures 1 and 2

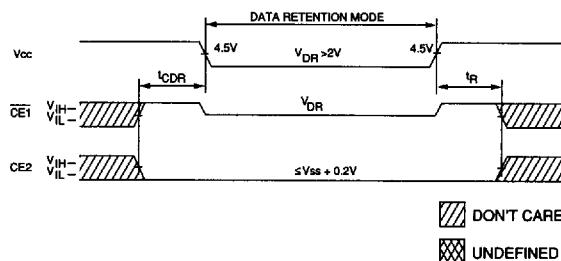
NOTES

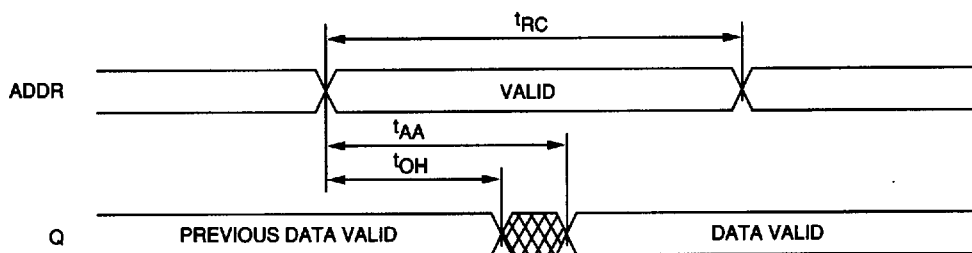
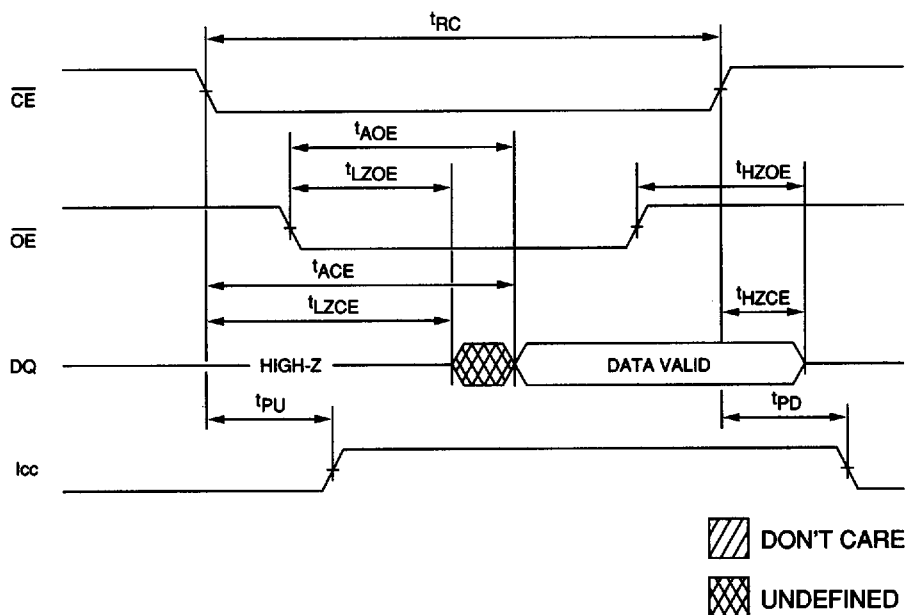
1. All voltages referenced to Vss (GND).
2. -3V for pulse width < $t_{RC}/2$.
3. I_{CC} is dependent on output loading and cycle rates.
4. This parameter is sampled.
5. Test conditions as specified with the output loading as shown in Fig. 1 unless otherwise noted.
6. t_{HZCE} , t_{HZOE} and t_{HZWE} are specified with $CL = 5pF$ as in Fig. 2. Transition is measured $\pm 500mV$ from steady state voltage.
7. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} and t_{HZWE} is less than t_{LZWE} .
8. \overline{WE} is HIGH for READ cycle.
9. Device is continuously selected. All chip enables and output enables are held in their active state.
10. Address valid prior to, or coincident with, latest occurring chip enable.
11. t_{RC} = Read Cycle Time.
12. $CE2$ timing is the same as $\overline{CE1}$ timing. The wave form is inverted.
13. Chip enable and write enable can initiate and terminate a WRITE cycle.
14. Refer to the IT/XT/AT section of Micron's SRAM Data Book for applicable non-commercial temperature range specifications.
15. Typical values are measured at 5V, 25°C and 25ns cycle time.

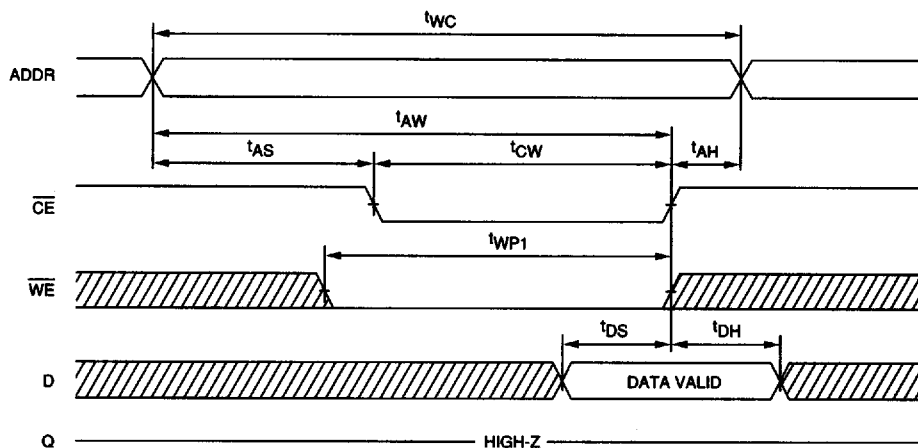
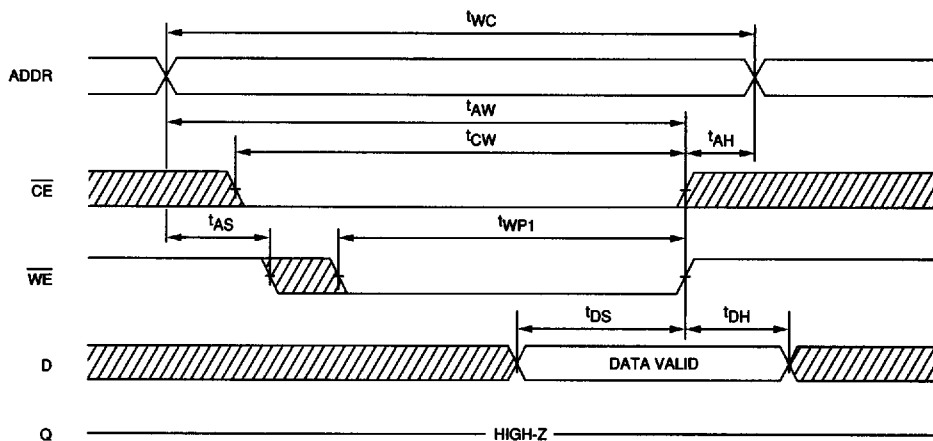
DATA RETENTION ELECTRICAL CHARACTERISTICS (L and LP Versions Only)

DESCRIPTION	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Vcc for Retention Data		V_{DR}	2			V	
Data Retention Current	$\overline{CE1} \geq (V_{CC} - 0.2V)$	$V_{CC} = 2V$	I_{CCDR}	35	150	μA	
	or $CE2 \leq (V_{SS} + 0.2V)$	$V_{CC} = 3V$		60	250	μA	
	$V_{IN} \geq (V_{CC} - 0.2V)$ or $\leq 0.2V$	$V_{CC} = 3V^*$		30	100	μA	
Chip Deselect to Data Retention Time		t_{CDR}	0			ns	4
Operation Recovery Time		t_R	t_{RC}			ns	4, 11

*Preliminary

LOW Vcc DATA RETENTION WAVEFORM


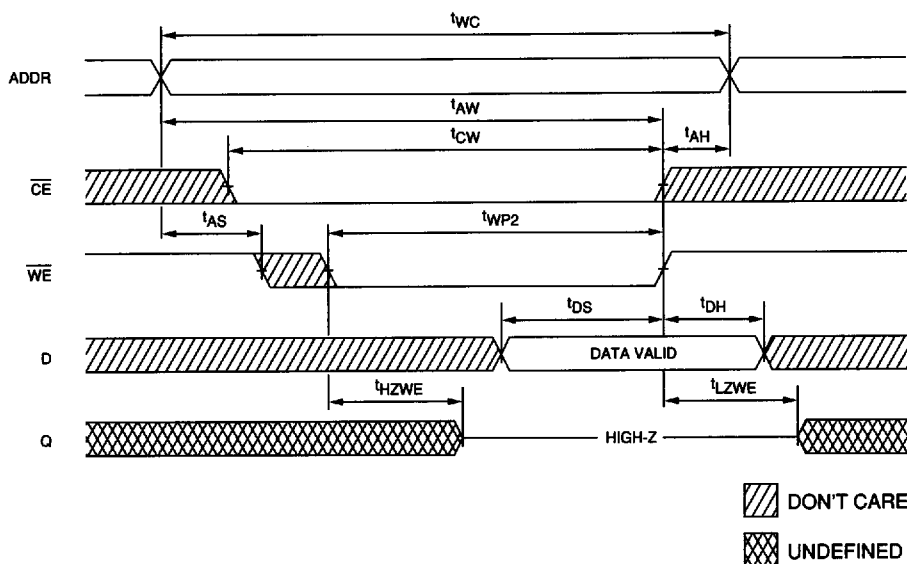
MICRON**MT5C1008**
128K x 8 SRAM**T-46-23-14****READ CYCLE NO. 1^{8,9}****READ CYCLE NO. 2^{7,8,10,12}**

MICRON**MT5C1008
128K x 8 SRAM****T-46-23-14****WRITE CYCLE NO. 1¹²**
(Chip Enable Controlled)**WRITE CYCLE NO. 2^{12, 13}**
(Write Enable Controlled)

DON'T CARE

UNDEFINED

NOTE: Output enable (\overline{OE}) is inactive (HIGH).

MICRON**MT5C1008**
128K x 8 SRAM**T-46-23-14****WRITE CYCLE NO. 3 7, 12, 13**
(Write Enable Controlled)**NOTE:** Output enable (\overline{OE}) is active (LOW).